

	Type	L #	Hits	Search Text	DBS	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	431	438/612.cccls.	USPAT; US-PCGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 13:35			0
2	BRS	L2	1599	438/612.cccls.	USPAT; US-PCGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:41			0
3	BRS	L3	272	L2 and solder	USPAT; US-PCGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 13:36			0
4	BRS	L4	493	L2 and electrode	USPAT; US-PCGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 13:36			0
5	BRS	L5	43	L2 and (electrode with solder)	USPAT; US-PCGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 13:36			0
6	BRS	L6	435	438/613.cccls.	USPAT; US-PCGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 13:44			0
7	BRS	L7	342	L6 and solder	USPAT; US-PCGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 14:09			0
8	BRS	L8	687	257/738.cccls.	USPAT; US-PCGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 14:11			0
9	BRS	L9	635	L8 not L6	USPAT; US-PCGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 14:11			0

	Type	L #	Hits	Search Text	DBS	Time Stamp	Comments	Error Definition	Errors
10	BRS	L10	635	L9 not L1	USPAT; US-EGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 14:11			0
11	BRS	L11	633	L9 not L1	USPAT; US-EGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 14:11			0
12	BRS	L12	631	L9 not L3	USPAT; US-EGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:05			0
13	BRS	L13	7108	flange and solder	USPAT; US-EGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:06			0
14	BRS	L14	6291	L13 and (perature or hole or through)	USPAT; US-EGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 16:11			0
15	BRS	L15	143	257/732.ccls.	USPAT; US-EGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:41			0
16	BRS	L16	50	L15 and soilder	USPAT; US-EGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:12			0
17	BRS	L17	25	L15 and air	USPAT; US-EGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:16			0

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
18 BRS	L18	8656	(land or electrode) same air	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:17			0
19 BRS	L19	195	118 and solder	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:18			0
20 BRS	L20	0	12 and sir	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:41			0
21 BRS	L21	103	L2 and air	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:55			0
22 BRS	L22	9	porous adj land	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:57			0
23 BRS	L23	1338	(air adj vent\$) and (land or electrode)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 15:59			
24 BRS	L24	130	air adj vent\$) with (land or electrode)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 16:38		Truncation Overflow. Return string from Server is: 5'2121618	1
25 BRS	L25	728183	((aperture or hole or through or gap or space) with air)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 16:13		Truncation Overflow. Return string from Server is: 5'2121618	0

Type	I #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
26 BRS	L26	496	L25 and ((land or electrode) same (solder or ball or bump))	USPAT; US-PGPU B; EPO; 2002/01/07 16:16 ; IBM TDB				0
27 BRS	L27	218	L26 and (vent or release or escape)	USPAT; US-PGPU B; EPO; 2002/01/07 16:48 ; IBM TDB				0
28 BRS	L28	4984	slit with (land or electrode)	USPAT; US-PGPU B; EPO; 2002/01/07 16:47 ; IBM TDB				0
29 BRS	L29	227	L28 and solder	USPAT; US-PGPU B; EPO; 2002/01/07 16:39 ; IBM TDB				0
30 BRS	L30	31262	(recess or cavity) with (land or electrode or pad)	USPAT; US-PGPU B; EPO; 2002/01/07 16:47 ; IBM TDB				0
31 BRS	L31	1886	L30 and solder	USPAT; US-PGPU B; EPO; 2002/01/07 16:18 ; IBM TDB				0
32 BRS	L32	305	L31 and (vent or release or escape)	USPAT; US-PGPU B; EPO; 2002/01/07 16:51 ; IBM TDB				0
33 BRS	L33	581	257/738.cc1s. and solder	USPAT; US-PGPU B; EPO; 2002/01/07 16:52 ; IBM TDB				0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errno
34	BRS	L35	321	257/786.cccls. and solder	USPAT; US-PGPU; B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 16:52			0
35	BRS	L36	410	257/780.cccls. and solder	USPAT; US-PGPU; B; EPO; JPO; DERWENT ; IBM	2002/01/07 16:52			0
36	BRS	L37	38	257/739.cccls. and solder	TDB				
37	BRS	L34	491	257/779.cccls. and solder	USPAT; US-PGPU; B; EPO; JPO; DERWENT ; IBM TDB	2002/01/07 16:58			0